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(54) **Title**: APPARATUS AND METHOD FOR BATCH NON-CONTACT MATERIAL CHARACTERIZATION

(57) **Abstract**: An apparatus for performing non-contact material characterization includes a wafer carrier (10) adapted to hold a plurality of substrates (12) and a material characterization device (20), such as a device for performing photoluminescence spectroscopy. The apparatus is adapted to perform non-contact material characterization on at least a portion of the wafer carrier (10), including the substrates (12) disposed thereon.

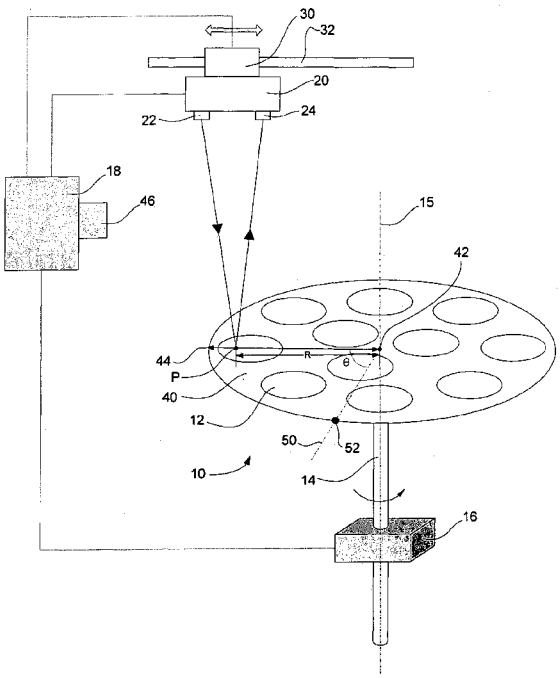


FIG. 1

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